



QUICK SPEC

STRUCTURAL CONCRETE

Elastuff® 101 with Elastuff® 103

NOTE: The following "Quick Spec" is an abbreviated specification and is not meant to replace the detailed specification. Read the entire 3-Part CSI System Specification prior to starting the project.

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|---------------------------------|---|
| Method | <ul style="list-style-type: none"> Spray, roller, or brush |
| Requirements | <ul style="list-style-type: none"> Moisture survey recommended. Roof must be clean, dry, and tight. Adhesion test required to ensure proper adhesion to substrate(s). Apply at 50°F (10°C) and rising with no rain, dew, fog or freezing temperatures in forecast for 24 hours. GAF recommends that the surface temperature be at or less than 110°F (43°C) during application. Concrete must be fully cured (typically 28 days). |
| Application Instructions | <ol style="list-style-type: none"> Before applying Elastuff® 101 with Elastuff® 103, an adhesion test is required to ensure an adhesion minimum of 2.0 PLI. Test patches to be applied with rates listed below. Conduct moisture survey and remove/replace all wet areas. Repair or replace damaged or deteriorated sections with like materials, allowing cementitious products to cure properly. Power-wash roof. United Cleaning Concentrate (UCC) is recommended to clean the roof. Allow the roof to completely dry. Prime with UniTile LV Sealer. Treat expansion joints with backer rod and compatible sealant. Then treat with Elastuff® 101 and Fabric. Treat all roof penetrations, drains, curbs, and scuppers. Treat all seams. Apply coating per the chart below: |

STRUCTURAL CONCRETE ELASTUFF® 101/103									
Warranty Term	Elastuff® 101		Elastuff® 103			System		Warranty	
	Base Coat (Gal/Sq)	DFT* (mils)	1ST Coat (Gal/Sq)	2nd Coat (Gal/Sq)	DFT* (mils)	Total (Gal/Sq)	DFT* (mils)	Emerald Pledge	Diamond Pledge
10 Year	1.50	19	1.50		14	3.00	33	Yes	No
15 Year	1.50	19	1.00	1.25	21	3.75	40	Yes	No

* DFT (Dry Film Thickness) is rounded to nearest mil and is theoretical. Actual DFT will vary dependent on substrate profile, application technique & waste factor.